FIG. 1

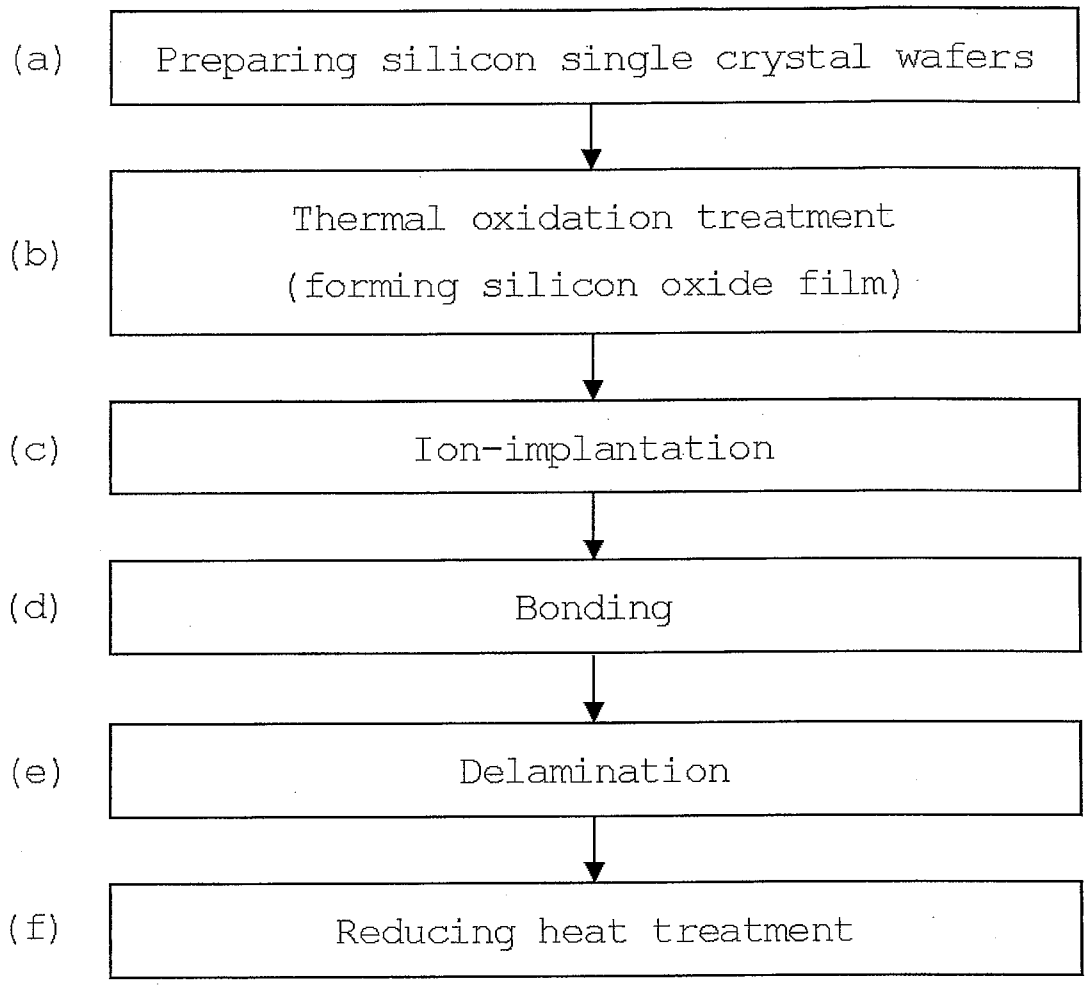
(a)
Preparing silicon single crystal wafers
(b)
Thermal oxidation treatment
(forming silicon oxide film)
(c)
Ion-implantation
(d)
Bonding
(e)
Delamination
(f)
Reducing heat treatment

FIG. 2

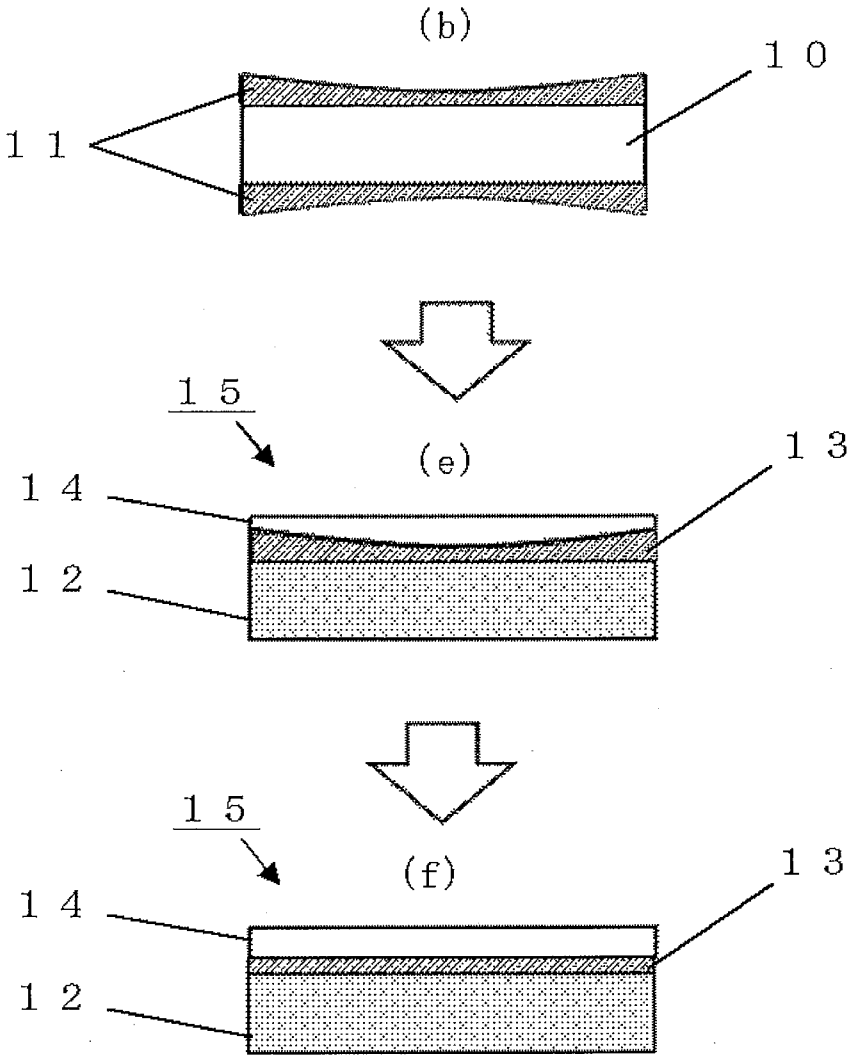
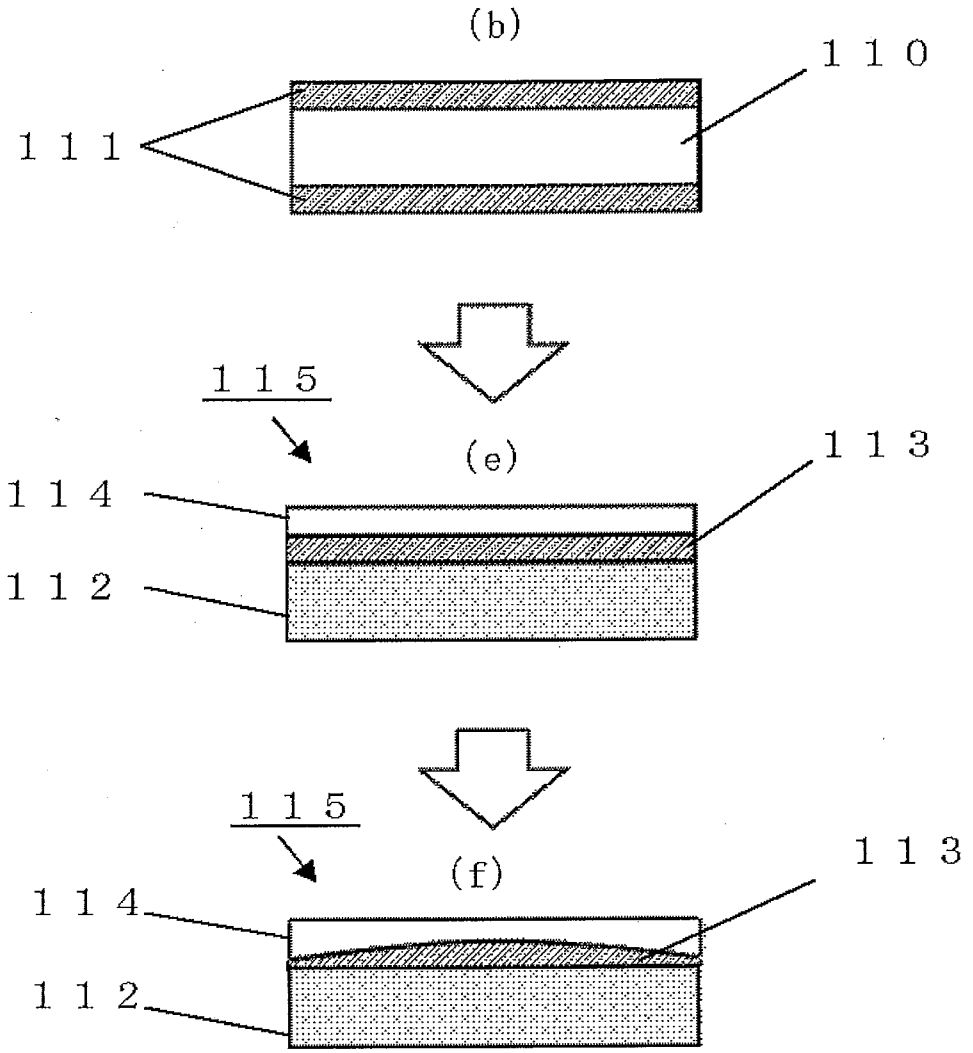
FIG. 3